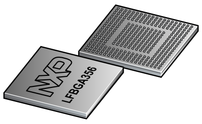


SOT1519-1

LFBGA356; plastic, low profile fine-pitch ball grid array; 356 bumps; 0.8 mm pitch; 17 mm x 17 mm x 1.54 mm body

24 July 2019 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA356
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-06-2019
Manufacturer package code	98ASA00478D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	1.54	1.7	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	356	-	

2 Package outline

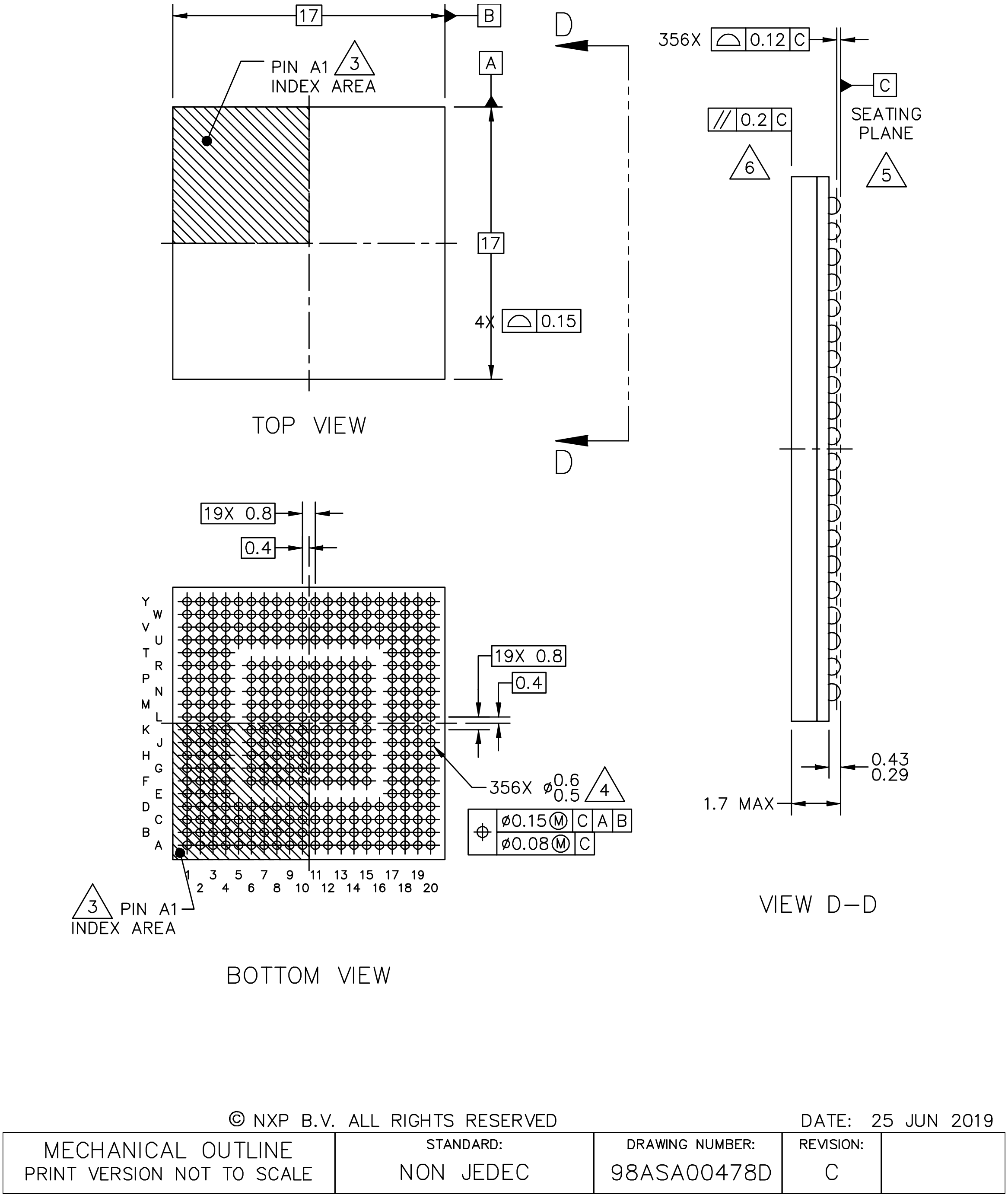
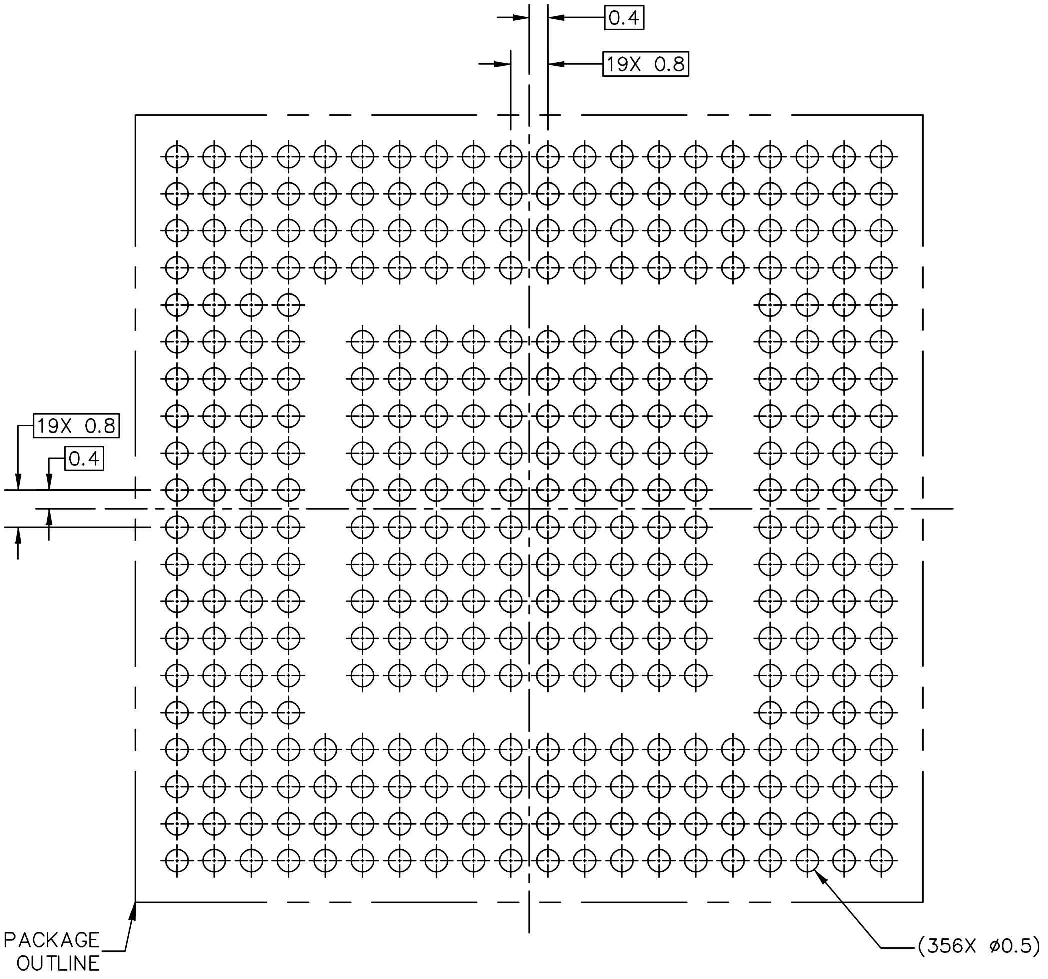


Figure 1. Package outline LFBGA356 (sot1519-1)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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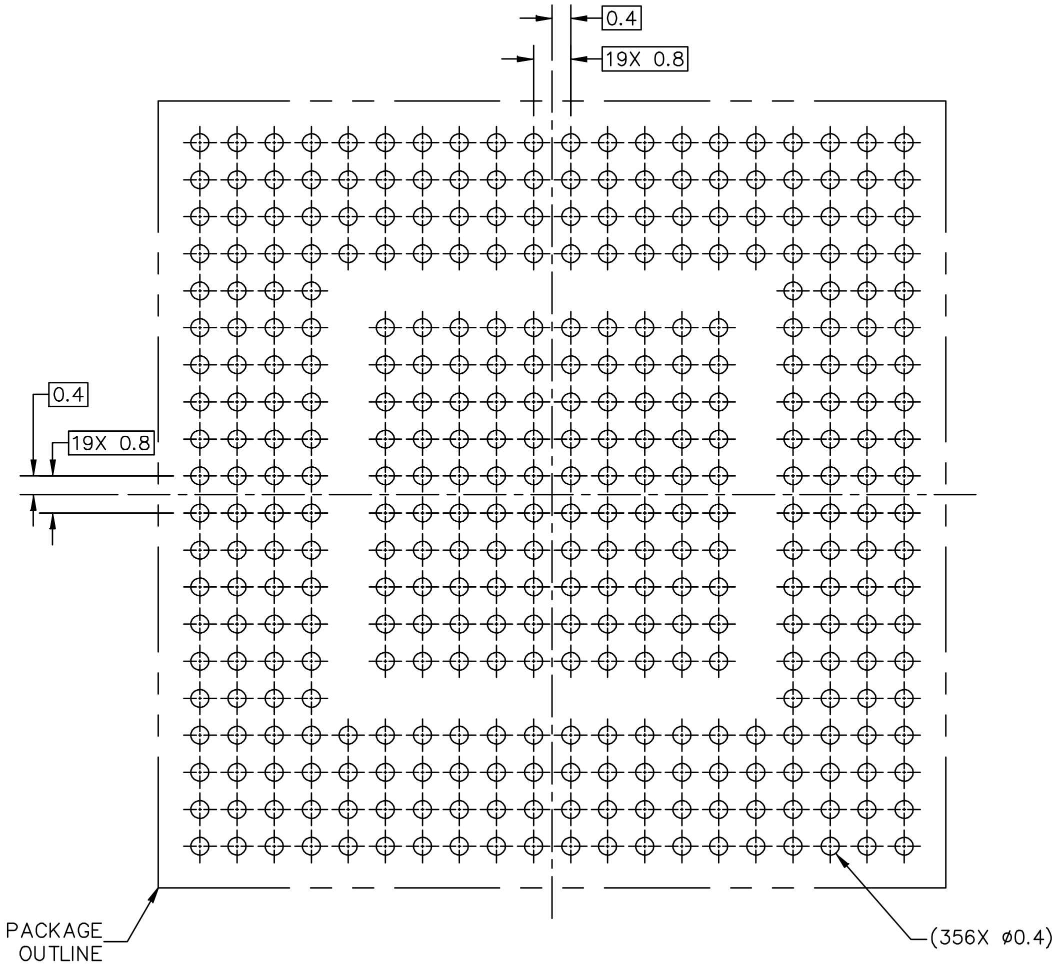
DATE: 25 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD:	DRAWING NUMBER:	REVISION:	
	NON JEDEC	98ASA00478D	C	

Figure 2. Reflow soldering footprint part1 of LFBGA356 (SOT1519-1)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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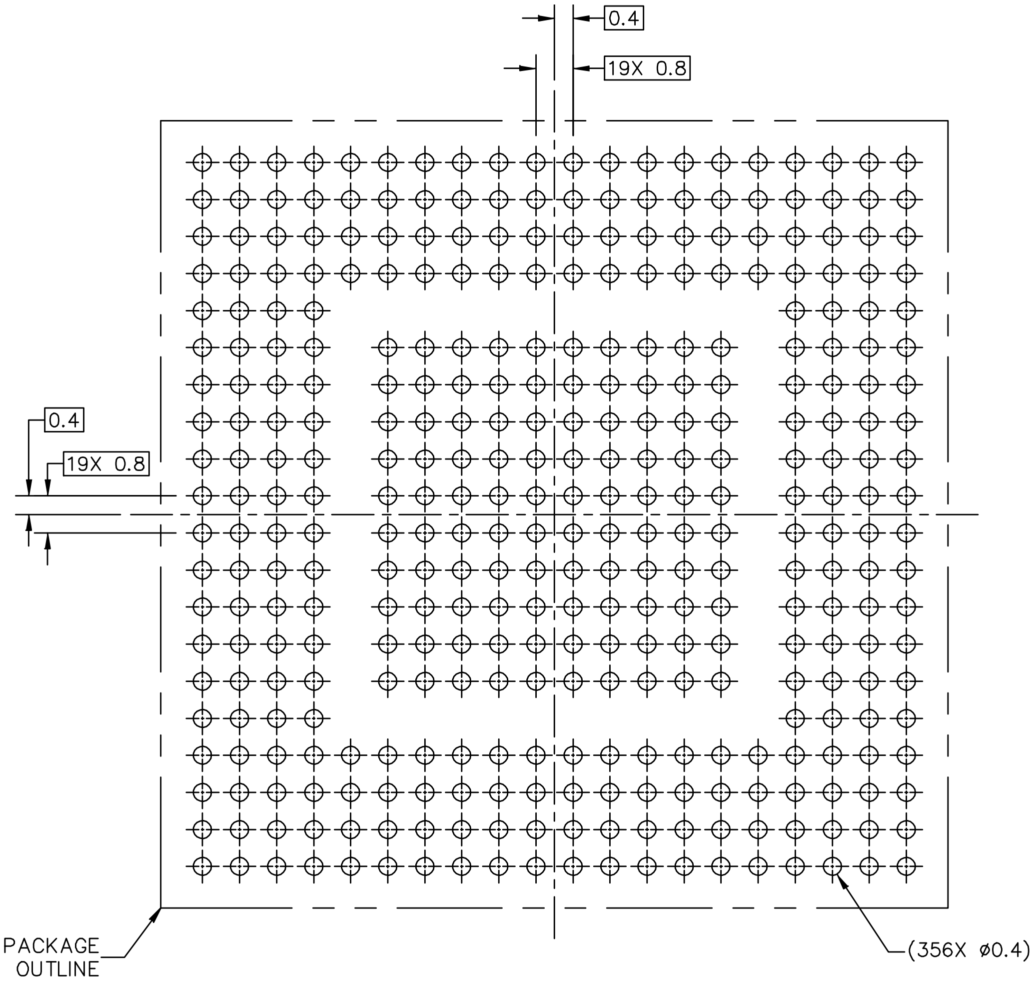
DATE: 25 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA00478D	REVISION: C	

Figure 3. Reflow soldering footprint part2 of LFBGA356 (SOT1519-1)

LFBGA356; plastic, low profile fine-pitch ball grid array; 356 bumps; 0.8 mm pitch; 17 mm x 17 mm x 1.54 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 25 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA00478D	REVISION: C	

Figure 4. Reflow soldering footprint part3 of LFBGA356 (SOT1519-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

DATE: 25 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA00478D	REVISION: C	

Figure 5. Package outline note LFBGA356 (sot1519-1)

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Date of release: 24 July 2019